CLAIMS:

1. A method of manufacturing a display device, in which a substrate is provided with groups of at least one pixel and a conductor pattern and in which a semiconductor device for supplying drive voltages to the pixel is fixed to the substrate, the method comprising the steps of

providing a semiconductor substrate with a plurality of semiconductor devices having electric connection contacts on their surfaces,

mutually separating the semiconductor devices in a surface region of the semiconductor substrate,

coupling the electric connection contacts to the conductor pattern, and

subsequently separating the semiconductor devices from the semiconductor substrate.

2. A method as claimed in claim 1, wherein at least a part of the electric connection contacts is connected to the conductor pattern in an electrically conducting manner.

3. A method of manufacturing a display device, in which a substrate is provided with groups of at least one pixel and in which a semiconductor device for supplying drive voltages to the pixel is fixed to the substrate, the method comprising the steps of

providing a semiconductor substrate with a plurality of semiconductor devices having electric connection contacts on their surfaces,

mutually separating the semiconductor devices in a surface region of the semiconductor substrate,

subsequently separating the semiconductor devices from the semiconductor substrate, and

subsequently providing the substrate with a conductor pattern at least at the location of the semiconductor devices and coupling the electric connection contacts to the conductor pattern.

4. A method as claimed in claim 3, wherein at least a part of the electric connection contacts is connected to the conductor pattern in an electrically conducting manner.

5. A method as claimed in claim 1 or 3, wherein the semiconductor devices have the same pitch as the groups of pixels in at least one dimension.

6. A method as claimed in claim 1 or 3, wherein a semiconductor device is associated with a plurality of pixels.

7. A method as claimed in claim 6, wherein the semiconductor device comprises drive electronics for the pixels.

8. A method as claimed in claim 1 or 3, wherein the semiconductor devices are separated by means of an etching treatment in a surface region of the semiconductor substrate.

9. A method as claimed in claim 1 or 3, wherein the semiconductor devices are provided in a semiconductor layer on an insulating layer (19) and are separated by means of an etching treatment.

10. A method as claimed in claim 1 or 3, wherein the substrate is flexible.

11. A method of manufacturing an electronic device, in which at least a substrate is provided with functional groups comprising at least a switching element, and in which a semiconductor device for supplying drive voltages to the switching element is fixed to the substrate, the method comprising the steps of

providing the substrate with a conductor pattern,

providing a semiconductor substrate with a plurality of semiconductor devices having electric connection contacts on their surfaces,

mutually separating the semiconductor devices in a surface region of the semiconductor substrate,

coupling the electric connection contacts to the conductor pattern, and

subsequently separating the semiconductor devices from the semiconductor substrate.

12. A method as claimed in claim 11, wherein at least a part of the electric connection contacts is connected to the conductor pattern in an electrically conducting manner.

13. A method of manufacturing an electronic device, in which at least a substrate is provided with functional groups comprising at least a switching element, and in which a semiconductor device for supplying drive voltages to the switching element is fixed to the substrate, the method comprising the steps of

providing a semiconductor substrate with a plurality of semiconductor devices having electric connection contacts on their surfaces,

mutually separating the semiconductor devices in a surface region of the semiconductor substrate,

subsequently separating the semiconductor devices from the semiconductor substrate, and

providing the substrate with a conductor pattern and coupling the electric connection contacts to the conductor pattern.

14. A method as claimed in claim 13, wherein at least a part of the electric connection contacts is connected to the conductor pattern in an electrically conducting manner.

15. A method as claimed in claim 11 or 13, wherein the semiconductor devices have the same pitch as the functional groups in at least one dimension.